

## JF-18 FLUX CORED WIRE TDS

- Halogen Free
- Excellent Spread Factor & Low Smoke
- Minimal Spattering
- High-Quality Solder Joint
- Applicable with Robotic & Manual Soldering
- Good Wetting & Excellent Solderability
- Minimal Spattering

### DESCRIPTION

PAI JF-18 cored flux is a premium, RoHS-compliant formulation, engineered to meet the demanding standards of modern electronics manufacturing. This JF-18 formulation is specially designed for lead-free alloys. Formulated with high-purity virgin raw metals, it is processed using cutting-edge Vaccualloy Technology, ensuring world-class quality and performance. This advanced process eliminates oxygen interaction with the alloy, significantly reducing dross formation during PCB assembly. As a result, manufacturers benefit from improved flow rates, lower impurity levels, and cleaner solder joints. PAI JF-18 is fully compatible with a broad range of flux formulations commonly used across the electronics industry, making it a versatile solution for various soldering applications.

### CLEANING

JF-18 residues do not require cleaning. In case, in application when cleaning is required, use PAI-Thinner.

### HANDLING & STORAGE

DURATION	TEMPERATURE
3 years	Room Temperature

### STANDARD AVAILABILITY

The JF-18 flux-cored wire formulation is available across a full range of lead-free solder alloys, including SAC0307, SAC305, and Sn99.3/Cu0.7, among others. Flux Core Percentage is available as per customer's specification. Custom diameters from 2 mm to 0.3 mm are available. Spool size available in 0.250 kgs & 0.500 kgs.

### ALLOY

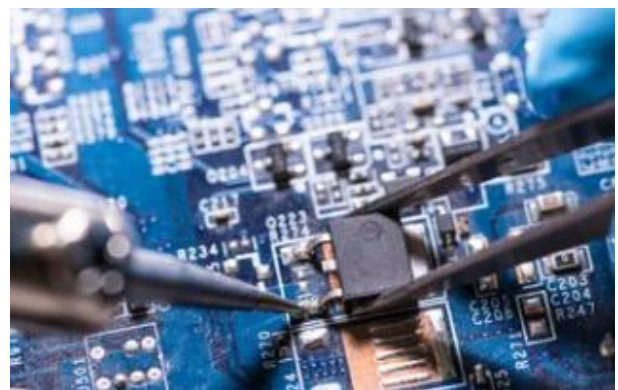
JF-18 is compatible with Sn99.3/Cu0.7, SAC0307 & SAC305.

### APPLICATION



JF-18 is compatible with standard industry soldering profiles and offers excellent performance across a variety of PCB surface finishes. The maintained temperature of solder iron tip should be between 370°C-430°C. Excellent wettability as no external flux is required.

### SAFETY

Ensure adequate ventilation during use. Always wear appropriate personal protective equipment (PPE). Consult the Safety Data Sheet (SDS) for detailed emergency procedures. Dispose of hazardous materials only in approved containers.



**TEST DATA SUMMARY**

NAME	TEST METHOD	RESULTS	
IPC Flux Classification	J-STD-004	ROL0	
NAME	TEST METHOD	TYPICAL RESULTS	IMAGE
Copper Mirror	JIS Z 3197	PASS	
Corrosion	JIS Z 3197	PASS	
Quantitative Halides	JIS Z 3197	PASS	
Qualitative Halides, Fluoride Spot	JIS Z 3197	PASS	
Surface Insulation Resistance (SIR)	JIS Z 3197	PASS	
Acid Value Determination	IS 1921:2005	210±10 mg KOH/ g	
Visual	J-STD-004B 3.4.2.5	PASS	
Spread	JIS Z 3197	PASS	

For more information, please visit our website at [www.pai-aimsolder.com](http://www.pai-aimsolder.com) or write us on support@pai-aimsolder.com

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